

#### USB251xB/xBi

# **USB 2.0 Hi-Speed Hub Controller**

#### PRODUCT FEATURES

**Data Sheet** 

#### **General Description**

The Microchip USB251xB/xBi hub is a family of low-power, configurable, MTT (multi transaction translator) hub controller IC products for embedded USB solutions. The *x* in the part number indicates the number of downstream ports available, while the *B* indicates battery charging support. The Microchip hub supports low-speed, full-speed, and hi-speed (if operating as a hi-speed hub) downstream devices on all of the enabled downstream ports.

#### **Highlights**

- High performance, low-power, small footprint hub controller IC with 2, 3, or 4 downstream ports
- Fully compliant with the USB 2.0 Specification [1]
- Enhanced OEM configuration options available through either a single serial I<sup>2</sup>C<sup>®</sup> EEPROM, or SMBus slave port

#### ■ MultiTRAK™

 High-performance multiple transaction translator which provides one transaction translator per port

#### PortMap

Flexible port mapping and disable sequencing

#### PortSwap

 Programmable USB differential-pair pin locations ease PCB design by aligning USB signal lines directly to connectors

#### PHYBoost

 Programmable USB signal drive strength for recovering signal integrity using 4-level driving strength resolution

#### **Features**

- USB251xB/xBi products are fully footprint compatible with USB251x/xi/xA/xAi products as direct drop-in replacements
  - Cost savings include using the same PCB components and application of USB-IF Compliance by Similarity
- Full power management with individual or ganged power control of each downstream port
- Fully integrated USB termination and pull-up/pulldown resistors
- Supports a single external 3.3 V supply source; internal regulators provide 1.2 V internal core voltage
- Onboard 24 MHz crystal driver or external 24 MHz clock input
- Customizable vendor ID, product ID, and device ID
- 4 kilovolts of HBM JESD22-A114F ESD protection (powered and unpowered)
- Supports self- or bus-powered operation
- Supports the USB Battery Charging specification Rev. 1.1 for Charging Downstream Ports (CDP)
- The USB251xB/xBi offers the following package:
   36-pin QFN (6x6 mm) RoHS compliant package
- USB251xBi products support the industrial temperature range of -40°C to +85°C
- USB251xB products support the extended commercial temperature range of 0°C to +85°C

#### **Applications**

- LCD monitors and TVs
- Multi-function USB peripherals
- PC motherboards
- Set-top boxes, DVD players, DVR/PVR
- Printers and scanners
- PC media drive bay
- Portable hub boxes
- Mobile PC docking
- Embedded systems

#### **Order Numbers:**

ORDER NUMBERS*	ROHS COMPLIANT PACKAGE	PACKAGE SIZE (MM)	TEMPERATURE RANGE
USB2512B-AEZG USB2513B-AEZC USB2514B-AEZC	36-QFN	00.0 5	0°C to 85°C
USB2512Bi-AEZG USB2513Bi-AEZG USB2514Bi-AEZG		6x6x0.5	-40°C to 85°C

<sup>\*</sup> Add -TR to the end of any QFN order number to order tape and reel (36-pin packages only). Reel size is 3,000 pieces.

This product meets the halogen maximum concentration values per IEC61249-2-21

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**Data Sheet** 

# **Conventions**

Within this manual, the following abbreviations and symbols are used to improve readability.

Example	Description	
BIT	Name of a single bit within a field	
FIELD.BIT	Name of a single bit (BIT) in FIELD	
xy	Range from x to y, inclusive	
BITS[m:n]	Groups of bits from m to n, inclusive	
PIN	Pin Name	
zzzzb	Binary number (value zzzz)	
0xzzz	Hexadecimal number (value zzz)	
zzh	Hexadecimal number (value zz)	
rsvd	Reserved memory location. Must write 0, read value indeterminate	
code	Instruction code, or API function or parameter	
Section Name	Section or Document name	
Х	Don't care	
<parameter></parameter>	<> indicate a Parameter is optional or is only used under some conditions	
{,Parameter}	Braces indicate Parameter(s) that repeat one or more times	
[Parameter]	Brackets indicate a nested Parameter. This Parameter is not real and actually decodes into one or more real parameters.	

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# **Chapter 1 Overview**

The Microchip USB251xB/xBi hub family is a group of low-power, configurable, MTT (multi transaction translator) hub controller ICs. The hub provides downstream ports for embedded USB solutions and is fully compliant with the *USB 2.0 Specification* [1]. Each of the hub controllers can attach to an upstream port as a full-speed or full-/hi-speed hub. The hub can support low-speed, full-speed, and hispeed downstream devices when operating as a hi-speed hub.

All required resistors on the USB ports are integrated into the hub. This includes all series termination resistors and all required pull-down and pull-up resistors on D+ and D- pins. The over-current sense inputs for the downstream facing ports have internal pull-up resistors.

The USB251xB/xBi hub family includes programmable features, such as:

- MultiTRAK<sup>TM</sup> Technology: implements a dedicated Transaction Translator (TT) for each port.
   Dedicated TTs help maintain consistent full-speed data throughput regardless of the number of active downstream connections.
- PortMap: provides flexible port mapping and disable sequences. The downstream ports of a USB251xB/xBi hub can be reordered or disabled in any sequence to support multiple platform designs with minimum effort. For any port that is disabled, the USB251xB/xBi hub controller automatically reorders the remaining ports to match the USB host controller's port numbering scheme.
- PortSwap: allows direct alignment of USB signals (D+/D-) to connectors to avoid uneven trace length or crossing of the USB differential signals on the PCB.
- PHYBoost: enables 4 programmable levels of USB signal drive strength in downstream port transceivers. PHYBoost will also attempt to restore USB signal integrity.

# 1.1 Configurable Features

The USB251xB/xBi hub controller provides a default configuration that may be sufficient for most applications. Strapping option pins (see Section 3.3.1 on page 20) provide additional features to enhance the default configuration. When the hub is initialized in the default configuration, the following features may be configured using the strapping options:

- Downstream non-removable ports, where the hub will automatically report as a compound device
- Downstream disabled ports
- Enabling of battery charging option on individual ports

The USB251xB/xBi hub controllers can alternatively be configured by an external  $I^2C$  EEPROM or a microcontroller as an SMBus slave device. When the hub is configured by an  $I^2C$  EEPROM or over SMBus, the following configurable features are provided:

- Support for compound devices on a port-by-port basis
- Selectable over-current sensing and port power control on an individual or ganged basis to match the circuit board component selection
- Customizable vendor ID, product ID, and device ID
- Configurable USB signal drive strength
- Configurable USB differential pair pin location
- Configurable delay time for filtering the over-current sense inputs
- Configurable downstream port power-on time reported to the host
- Indication of the maximum current that the hub consumes from the USB upstream port

- Indication of the maximum current required for the hub controller
- Custom string descriptors (up to 31 characters):

Product

Manufacturer

Serial number

Battery charging USB251xB/xBi products are fully footprint compatible with USB251x/xi/xA/xAi products:

Pin-compatible

Direct drop-in replacement

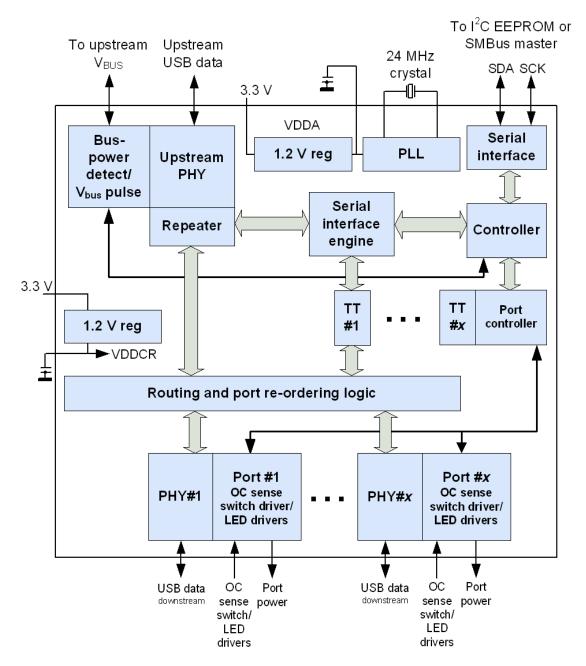
Use the same PCB components

USB-IF Compliance by Similarity for ease of use and a complete cost reduction solution Product IDs, device IDs, and other register defaults may differ. See Section 5.1 on page 25 for details.

Table 1.1 Summary of Compatibilities between USB251xB/xBi and USB251x/xi/xA/xAi Products

Part Number	Drop-in Replacement
USB2512	USB2512B
USB2512i	USB2512Bi
USB2512A	USB2512B
USB2512Ai	USB2512Bi
USB2513	USB2513B
USB2513i	USB2513Bi
USB2514	USB2514B
USB2514i	USB2514Bi

# **Chapter 2 Block Diagram**



x indicates the number of available downstream ports: 2, 3, or 4

Figure 2.1 USB251xB/xBi Hub Family Block Diagram

# **Chapter 3 Pin Information**

This chapter outlines the pinning configurations for each package type available, followed by a corresponding pin list organized alphabetically. The detailed pin descriptions are listed then outlined by function in Section 3.3: *Pin Descriptions (Grouped by Function)* on page 17.

## 3.1 Pin Configurations

The following figures detail the pinouts of the various USB251xB/xBi versions.

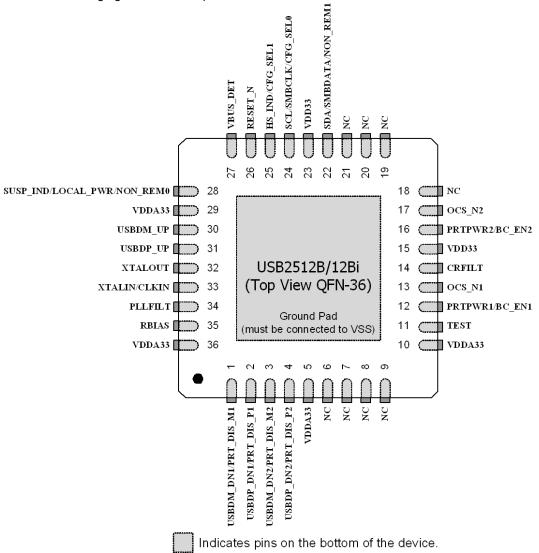


Figure 3.1 2-Port 36-Pin QFN

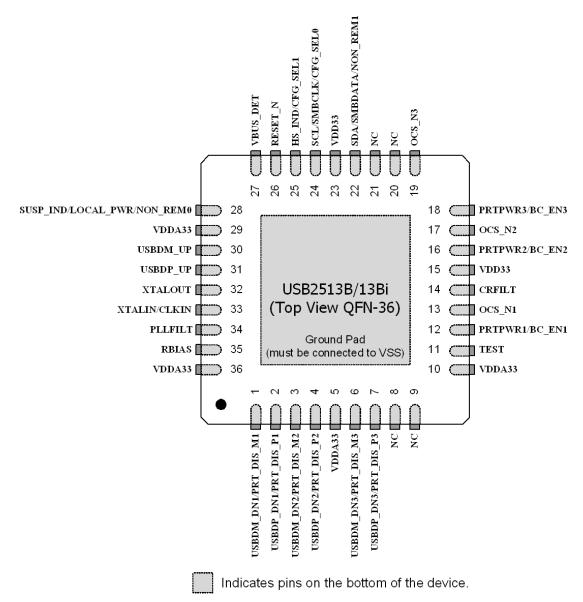


Figure 3.2 3-Port 36-Pin QFN

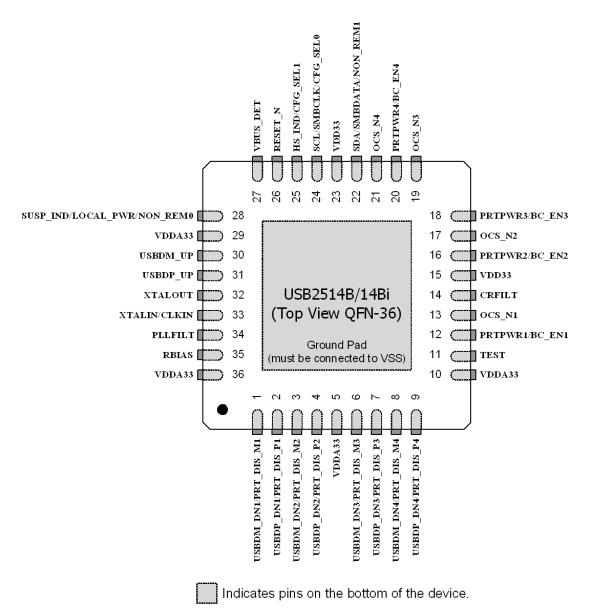


Figure 3.3 4-Port 36-Pin QFN

# 3.2 Pin List (Alphabetical)

Table 3.1 USB251xB/xBi Pin List (Alphabetical)

			PIN NUMBERS		
		36 QFN			
SYMBOL	NAME	USB2512B USB2512Bi	USB2513B USB2513Bi	USB2514B USB2514Bi	
BC_EN1	Battery Charging		12		
BC_EN2	Strap Option		16		
BC_EN3		-	1	8	
BC_EN4			-	20	
CFG_SEL0	Configuration		24		
CFG_SEL1	Programming Selection		25		
CLKIN	External Clock Input		33		
CRFILT	Core Regulator Filter Capacitor		14		
Ground Pad (VSS)	Exposed Pad Tied to Ground (VSS)	ePad			
HS_IND	Hi-Speed Upstream Port Indicator	25			
LOCAL_PWR	Local Power Detection	28			
NC	No Connect	6		-	
NC		7		-	
NC		18		-	
NC		19		-	
NC			8	-	
NC		!	9	-	
NC		2	20	-	
NC		21 -			
NON_REM0	Non-Removable		28		
NON_REM1	Port Strap Option	22			
OCS_N1	Over-Current Sense		13		
OCS_N2			17		
OCS_N3		-		9	
OCS_N4			-	21	
PLLFILT	PLL Regulator Filter Capacitor		34		

Table 3.1 USB251xB/xBi Pin List (Alphabetical) (continued)

		PIN NUMBERS			
		36 QFN			
SYMBOL	NAME	USB2512B USB2512Bi	USB2513B USB2513Bi	USB2514B USB2514Bi	
PRT_DIS_M1	Downstream Port		1		
PRT_DIS_M2	Disable Strap Option		3		
PRT_DIS_M3	Οριίοπ .	-	(	6	
PRT_DIS_M4			-	8	
PRT_DIS_P1	Port Disable		2		
PRT_DIS_P2			4		
PRT_DIS_P3		-	7	7	
PRT_DIS_P4	<u>                                       </u>			9	
PRTPWR1	USB Port Power		12		
PRTPWR2	Enable		16		
PRTPWR3		-	1	8	
PRTPWR4			-	20	
RBIAS	USB Transceiver Bias		35		
RESET_N	Reset Input		26		
SCL	Serial Clock		24		
SDA	Serial Data Signal		22		
SMBCLK	System Management Bus Clock		24		
SMBDATA	System Management Bus Data Signal		22		
SUSP_IND	Active/Suspend Status Indicator		28		
TEST	Test Pin		11		
USBDM_UP	USB Bus Data		30		
USBDP_UP			31		
USBDM_DN1	Hi-Speed USB Data		1		
USBDM_DN2	]		3		
USBDM_DN3	]	-	(	6	
USBDM_DN4	]		-	8	
USBDP_DN1	]		2		
USBDP_DN2	]		4		
USBDP_DN3	]	-	-	7	
USBDP_DN4			-	9	

Table 3.1 USB251xB/xBi Pin List (Alphabetical) (continued)

		PIN NUMBERS		
			36 QFN	
SYMBOL	NAME	USB2512B USB2512Bi	USB2513B USB2513Bi	USB2514B USB2514Bi
VBUS_DET	Upstream VBUS Power Detection		27	
VDD33	3.3 V Digital Power		15	
VDD33			23	
VDDA33	3.3 V Analog Power		5	
VDDA33			10	
VDDA33			29	
VDDA33			36	
XTALIN	Crystal Input		33	
XTALOUT	Crystal Output		32	

## 3.3 Pin Descriptions (Grouped by Function)

An N at the end of a signal name indicates that the active (asserted) state occurs when the signal is at a low voltage level. When the N is not present, the signal is asserted when it is at a high voltage level. The terms assertion and negation are used exclusively in order to avoid confusion when working with a mixture of active low and active high signals. The term assert, or assertion, indicates that a signal is active, independent of whether that level is represented by a high or low voltage. The term negate, or negation, indicates that a signal is inactive.

Table 3.2 USB251xB/xBi Pin Descriptions

SYMBOL	BUFFER TYPE	DESCRIPTION
		UPSTREAM USB 2.0 INTERFACES
USBDM_UP USBDP_UP	IO-U	USB Data: connect to the upstream USB bus data signals (host, port, or upstream hub).
VBUS_DET	I	Detect Upstream VBUS Power: detects the state of the upstream VBUS power. The hub monitors VBUS_DET to determine when to assert the internal D+ pull-up resistor: (signaling a connect event).
		When designing a detachable hub, this pin should be connected to VBUS on the upstream port via a 2:1 voltage divider. Two 100 k $\Omega$ resistors are suggested.
		For self-powered applications with a permanently attached host, this pin must be connected to a dedicated host control output, or connected to the 3.3 V domain that powers the host (typically VDD33).
		DOWNSTREAM USB 2.0 INTERFACES
USBDP_DN[x:1]/ PRT_DIS_P[x:1]	IO-U	Hi-Speed USB Data: connect to the downstream USB peripheral devices attached to the hub's port. To disable, use a 10 $k\Omega$ pull-up resistor to 3.3 V.
USBDM_DN[x:1]/ PRT_DIS_M[x:1]		Downstream Port Disable Strap Option: when enabled by package and configuration settings (see Table 5.1 on page 24), this pin is sampled at RESET_N negation to determine if the port is disabled.
		To disable a port, pull up both PRT_DIS_M[x:1] and PRT_DIS_P[x:1] pins for the corresponding port number(s). See Section 3.3.1, on page 20 for pull up details.
PRTPWR[x:1]/	O12	USB Power Enable: enables power to USB peripheral devices downstream.
BC_EN[x:1]	IPD	Battery Charging Strap Option: when enabled by package and configuration settings (see Table 5.1), the pin will be sampled at RESET_N negation to determine if ports [x:1] support the battery charging protocol. When supporting the battery charging protocol, the hub also supports external port power controllers. The battery charging protocol enables a device to draw the currents per the USB battery charging specification. See Section 3.3.1, on page 20 for strap pin details.
		Battery charging feature is supported for port <i>x</i> Battery charging feature is not supported for port <i>x</i>
OCS_N[x:1]	IPU	Over-Current Sense: input from external current monitor indicating an over-current condition.
RBIAS	I-R	USB Transceiver Bias: a 12.0 k $\Omega$ (+/- 1%) resistor is attached from ground to this pin to set the transceiver's internal bias settings.

Table 3.2 USB251xB/xBi Pin Descriptions (continued)

SYMBOL	BUFFER TYPE	DESCRIPTION		
	SERIAL PORT INTERFACES			
SDA/	I/OSD12	Serial Data Signal		
SMBDATA/		System Management Bus Signal		
NON_REM1		Non-Removable Port 1 Strap Option: when enabled by package and configuration options (see Table 5.1 on page 24), this pin will be sampled (in conjunction with LOCAL PWR/SUSP_IND/NON_REM0) at RESET_N negation to determine if ports [x:1] contain permanently attached (non-removable) devices:		
		NON_REM[1:0] = 00 : all ports are removable NON_REM[1:0] = 01 : port 1 is non-removable NON_REM[1:0] = 10 : ports 1 and 2 are non-removable NON_REM[1:0] = 11 : when available, ports 1, 2, and 3 are non-removable		
		When NON_REM[1:0] is chosen such that there is a non-removable device, the hub will automatically report itself as a compound device (using the proper descriptors).		
RESET_N	IS	RESET Input: the system can reset the chip by driving this input low. The minimum active low pulse is 1 µs.		
SCL/	I/OSD12	I/OSD12 Serial Clock (SCL)		
SMBCLK/		System Management Bus Clock		
CFG_SEL0		Configuration Select: the logic state of this multifunction pin is internally latched on the rising edge of RESET_N (RESET_N negation), and will determine the hub configuration method as described in Table 5.1.		
HS_IND/	I/O12	Hi-Speed Upstream Port Indicator: upstream port connection speed.		
		Asserted = the hub is connected at HS Negated = the hub is connected at FS		
		Note: When implementing an external LED on this pin, the active state is indicated above and outlined in Section 3.3.1.3, on page 21.		
CFG_SEL1		Configuration Programming Select 1: the logic state of this pin is internally latched on the rising edge of RESET_N (RESET_N negation), and will determine the hub configuration method as described in Table 5.1.		
	•	MISC		
XTALIN	ICLKx	Crystal Input: 24 MHz crystal.		
		This pin connects to either one terminal of the crystal or to an external 24 MHz clock when a crystal is not used.		
CLKIN		External Clock Input: this pin connects to either one terminal of the crystal or to an external 24 MHz clock when a crystal is not used.		
XTALOUT	OCLKx	Crystal Output: this is the other terminal of the crystal circuit with 1.2 V p-p output and a weak (< 1mA) driving strength. When an external clock source is used to drive XTALIN/CLKIN, leave this pin unconnected, or use with appropriate caution.		

Table 3.2 USB251xB/xBi Pin Descriptions (continued)

	BUFFER	
SYMBOL	TYPE	DESCRIPTION
SUSP_IND/	I/O	Active/Suspend Status LED: indicates USB state of the hub.
		Negated = unconfigured; or configured and in USB suspend Asserted = hub is configured and is active (i.e., not in suspend)
LOCAL_PWR/		Local Power: detects availability of local self-power source.
		Low = self/local power source is NOT available (i.e., the hub gets all power from the upstream USB VBus) High = self/local power source is available
NON_REM0		Non-Removable 0 Strap Option: when enabled by package and configuration settings (see Table 5.1 on page 24), this pin will be sampled (in conjunction with NON_REM[1]) at RESET_N negation to determine if ports [x:1] contain permanently attached (non-removable) devices:
		<b>Note:</b> When implementing an external LED on this pin, the active state is outlined below and detailed in Section 3.3.1.3, on page 21.
		NON_REM[1:0] = 00 : all ports are removable; LED is active high NON_REM[1:0] = 01 : port 1 is non-removable; LED is active low NON_REM[1:0] = 10 : ports 1 and 2 are non-removable; LED is active high NON_REM[1:0] = 11 : (when available) ports 1, 2, and 3 are non-removable; LED is active low
TEST	IPD	Test Pin: treat as a no connect pin or connect to ground. No trace or signal should be routed or attached to this pin.
	1	POWER, GROUND, and NO CONNECTS
CRFILT		VDD Core Regulator Filter Capacitor: this pin can have up to a 0.1 $\mu F$ low-ESR capacitor to VSS, or be left unconnected.
VDD33		3.3 V Power
VDDA33		3.3 V Analog Power
PLLFILT		PLL Regulator Filter Capacitor: this pin can have up to a 0.1 $\mu F$ low-ESR capacitor to VSS, or be left unconnected.
VSS		Ground Pad/ePad: the package slug is the only VSS for the device and must be tied to ground with multiple vias.
NC		No Connect: no signal or trace should be routed or attached to all NC pins.

#### 3.3.1 Configuring the Strap Pins

If a pin's strap function is enabled thru the hub configuration selection, (Table 5.1: *Initial Interface/Configuration Options* on page 24) the strap pins must be pulled either high or low using the values provided in Table 3.3. Each strap option is dependent on the pin's buffer type, as outlined in the sections that follow.

STRAP OPTION	RESISTOR VALUE	BUFFER TYPE	NOTES
Non-Removable	47 - 100 kΩ	I/O	
Internal Pull-Down	10 kΩ	IPD	<ul><li>Only applicable to port power pins</li><li>Contains a built-in resistor</li></ul>
LED	47 - 100 kΩ	I/O	

**Table 3.3 Strap Option Summary** 

#### 3.3.1.1 Non-Removable

If a strap pin's buffer type is I/O, an external pull-up or pull-down must be implemented as shown in Figure 3.4. Use Strap High to set the strap option to 1 and Stap Low to set the strap option to 0. When implementing the Strap Low option, no additional components are needed (i.e., the internal pull-down provides the resistor)

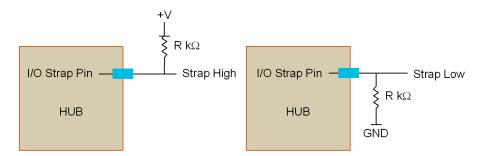


Figure 3.4 Non-Removable Pin Strap Example

#### 3.3.1.2 Internal Pull-Down (IPD)

If a strap pin's buffer type is IPD (pins  $BC_EN[x:1]$ ), one of the two hardware configurations outlined below must be implemented. Use the Strap High configuration to set the strap option value to 1 and Strap Low to set the strap option value to 0.

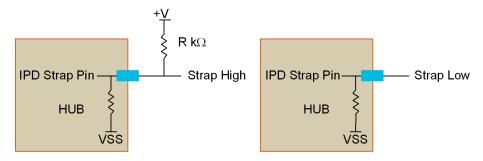


Figure 3.5 Pin Strap Option with IPD Pin Example

#### 3.3.1.3 LED

If a strap pin's buffer type is I/O and shares functionality with an LED, the hardware configuration outlined below must be implemented. The internal logic will drive the LED appropriately (active high or low) depending on the sampled strap option. Use the Strap High configuration to set the strap option value to 1 and Strap Low to set the strap option to 0.

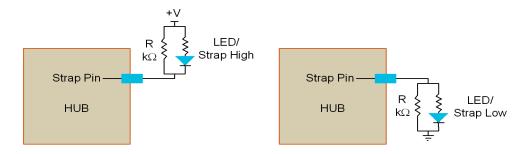


Figure 3.6 LED Pin Strap Example

## 3.4 Buffer Type Descriptions

**Table 3.4 Buffer Type Descriptions** 

BUFFER TYPE	DESCRIPTION
I	Input
I/O	Input/output
IPD	Input with internal weak pull-down resistor
IPU	Input with internal weak pull-up resistor
IS	Input with Schmitt trigger
O12	Output 12 mA
I/O12	Input/output buffer with 12 mA sink and 12 mA source
I/OSD12	Open drain with Schmitt trigger and 12 mA sink. Meets the I <sup>2</sup> C-Bus Specification [2] requirements.
ICLKx	XTAL clock input
OCLKx	XTAL clock output
I-R	RBIAS
I/O-U	Analog input/output defined in USB specification

# **Chapter 4 Battery Charging Support**

The USB251xB/xBi hub provides support for battery charging devices on a per port basis in compliance with the *USB Battery Charging Specification, Revision 1.1*. The hub can be configured to individually enable each downstream port for battery charging support either via pin strapping as illustrated in Figure 4.1 or by setting the corresponding configuration bits via I<sup>2</sup>C EEPROM or SMBus (Section 5.1 on page 25).

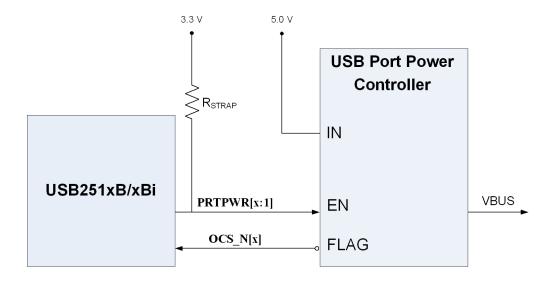


Figure 4.1 Battery Charging via External Power Supply

Note: R<sub>STRAP</sub> enables battery charging.

## 4.1 USB Battery Charging

A downstream port enabled for battery charging turns on port power as soon as the power on reset and hardware configuration process has completed. The hub does not need to be enumerated nor does VBUS\_DET need to be asserted for the port power to be enabled. These conditions allow battery charging in S3, S4, and S5 system power states as well as in the fully operational state. The USB Battery Charging Specification does not interfere with standard USB operation, which allows a device to perform battery charging at any time.

A port that supports battery charging must be able to support 1.5 amps of current on VBUS. Standard USB port power controllers typically only allow for 0.8 amps of current before detecting an over-current condition. Therefore, the 5 volt power supply, port power controller, or over-current protection devices must be chosen to handle the larger current demand compared to standard USB hub designs.

#### 4.1.1 Special Behavior of PRTPWR Pins

The USB251xB/xBi enables VBUS by asserting the port power (PRTPWR) as soon as the hardware configuration process has completed. If the port detects an over-current condition, PRTPWR will be turned off to protect the circuitry from overloading. If an over-current condition is detected when the hub is not enumerated, PRTPWR can only be turned on from the host or if RESET\_N is toggled. These

behaviors provide battery charging even when the hub is not enumerated and protect the hub from sustained short circuit conditions. If the short circuit condition persists when the hub is plugged into a host system the user is notified that a port has an over-current condition. Otherwise **PRTPWR** turned on by the host system and the ports operate normally.

### 4.2 Battery Charging Configuration

The battery charging option can be configured in one of two ways:

- When the hub is brought up in the default configuration with strapping options enabled, with the PRTPWR[x:1]/BC\_EN[x:1] pins configured. See the following sections for details:
  - Section 3.3: Pin Descriptions (Grouped by Function) on page 17
  - Section 3.3.1.2: Internal Pull-Down (IPD) on page 20
- When the hub is initialized for configuration over I<sup>2</sup>C EEPROM or SMBus. Either of these interfaces
  can be used to configure the battery charging option.

## 4.2.1 Battery Charging enabled via I<sup>2</sup>C EEPROM or SMBus

Register memory map location 0xD0 is allocated for battery charging support. The Battery Charging register at location 0xD0 starting from bit 1 enables battery charging for each downstream port when asserted. Bit 1 represents port 1, bit 2 represents port 2, etc. Each port with battery charging enabled asserts the corresponding PRTPWR[x:1] pin.

# **Chapter 5 Initial Interface/Configuration Options**

The hub must be configured in order to correctly function when attached to a USB host controller. The hub can be configured either internally or externally by setting the CFG\_SEL[1:0] pins (immediately after RESET\_N negation) as outlined in the table below.

**Note:** See Chapter 11 (Hub Specification) of the USB specification for general details regarding hub operation and functionality.

To configure the hub externally, there are two principal ways to interface to the hub: over SMBus or  $I^2C$  EEPROM. The hub can be configured internally, where several default configurations are available as described in the table below. When configured internally, additional configuration is available using the strap options (listed in Section 3.3.1 on page 20).

**Note:** Strap options are not available when configuring the hub over I<sup>2</sup>C or SMBus.

**Table 5.1 Initial Interface/Configuration Options** 

CFG_SEL[1]	CFG_SEL[0]	DESCRIPTION
0 0		Default configuration:  Strap options enabled  Self-powered operation enabled  Individual power switching  Individual over-current sensing
0	1	The hub is configured externally over SMBus (as an SMBus slave device):  Strap options disabled All registers configured over SMBus
1	0	Default configuration with the following overrides:  Bus-powered operation
1	1	The hub is configured over 2-wire I <sup>2</sup> C EEPROM:  Strap options disabled  All registers configured by I <sup>2</sup> C EEPROM

# 5.1 Internal Register Set (Common to I<sup>2</sup>C EEPROM and SMBus)

The register set available when configuring the hub to interface over I<sup>2</sup>C or SMBus is outlined in the table below. Each register has R/W capability, where EEPROM reset values are 0x00. Reserved registers should be written to 0 unless otherwise specified. Contents read from unavailable registers should be ignored.

ADDRESS	REGISTER NAME		LT ROM V	
		USB2512B/12Bi	USB2513B/13Bi	USB2514B/14Bi
00h	Vendor ID LSB		24	
01h	Vendor ID MSB		04	
02h	Product ID LSB	12	13	14
03h	Product ID MSB		25	
04h	Device ID LSB		В3	
05h	Device ID MSB		0B	
06h	Configuration Data Byte 1		9B	
07h	Configuration Data Byte 2		20	
08h	Configuration Data Byte 3		02	
09h	Non-Removable Devices		00	
0Ah	Port Disable (Self)		00	
0Bh	Port Disable (Bus)		00	
0Ch	Max Power (Self)		01	
0Dh	Max Power (Bus)		32	
0Eh	Hub Controller Max Current (Self)		01	
0Fh	Hub Controller Max Current (Bus)		32	
10h	Power-on Time		32	
11h	Language ID High		00	
12h	Language ID Low		00	
13h	Manufacturer String Length		00	
14h	Product String Length		00	
15h	Serial String Length		00	
16h-53h	Manufacturer String		00	

ADDRESS	REGISTER NAME	DEFAULT ROM VALUES (HEXIDECIMAL)		
		USB2512B/12Bi	USB2513B/13Bi	USB2514B/14Bi
54h-91h	Product String		00	
92h-CFh	Serial String		00	
D0h	Battery Charging Enable		00	
E0h	rsvd		00	
F5h	rsvd		00	
F6h	Boost_Up		00	
F7h	rsvd		00	
F8h	Boost_x:0		00	
F9h	rsvd		00	
FAh	Port Swap		00	
FBh	Port Map 12		00	
FCh	Port Map 34	-	0	0
FD-FEh	rsvd		00	
FFh	Status/Command Note: SMBus register only		00	

# 5.1.1 Register 00h: Vendor ID (LSB)

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	VID_LSB	Least Significant Byte of the Vendor ID: a 16-bit value that uniquely identifies the Vendor of the user device (assigned by USB-Interface Forum). Set this field using either the SMBus or I <sup>2</sup> C EEPROM interface options.

# 5.1.2 Register 01h: Vendor ID (MSB)

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	VID_MSB	Most Significant Byte of the Vendor ID: a 16-bit value that uniquely identifies the Vendor of the user device (assigned by USB-Interface Forum). Set this field using either the SMBus or I <sup>2</sup> C EEPROM interface options.

## 5.1.3 Register 02h: Product ID (LSB)

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	PID_LSB	Least Significant Byte of the Product ID: a 16-bit value that uniquely identifies the Product ID of the user device. Set this field using either the SMBus or I <sup>2</sup> C EEPROM interface options.

# 5.1.4 Register 03h: Product ID (MSB)

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	PID_MSB	Most Significant Byte of the Product ID: a 16-bit value that uniquely identifies the Product ID of the user device. Set this field using either the SMBus or I <sup>2</sup> C EEPROM interface options.

## 5.1.5 Register 04h: Device ID (LSB)

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	DID_LSB	Least Significant Byte of the Device ID: a 16-bit device release number in BCD format (assigned by OEM). Set this field using either the SMBus or I <sup>2</sup> C EEPROM interface options.

### 5.1.6 Register 05h: Device ID (MSB)

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	DID_MSB	Most Significant Byte of the Device ID: a 16-bit device release number in BCD format (assigned by OEM). Set this field using either the SMBus or I <sup>2</sup> C EEPROM interface options.

# 5.1.7 Register 06h: CONFIG\_BYTE\_1

5.1.7	Register U6n: C	ONFIG_B1TE_T
BIT NUMBER	BIT NAME	DESCRIPTION
7	SELF_BUS_PWR	Self or Bus Power: selects between self- and bus-powered operation.
		The hub is either self-powered (draws less than 2 mA of upstream bus power) or bus-powered (limited to a 100 mA maximum of upstream power prior to being configured by the host controller).
		When configured as a bus-powered device, the hub consumes less than 100 mA of current prior to being configured. After configuration, the bus-powered hub, along with all associated hub circuitry, any embedded devices (if part of a compound device), and all externally available downstream ports (max 100 mA) must consume no more than 500 mA of upstream VBUS current. The current consumption is system dependent and must not violate the <i>USB 2.0 Specification</i> [1].
		When configured as a self-powered device, < 1 mA of upstream VBUS current is consumed and all ports are available. Each port is capable of sourcing 500 mA of current.
		This field is set over either the SMBus or I <sup>2</sup> C EEPROM interface options.
		0 : bus-powered operation 1 : self-powered operation
		If dynamic power switching is enabled (Section 5.1.8), this bit is ignored and LOCAL_PWR is used to determine if the hub is operating from self or bus power.
6	rsvd	
5	HS_DISABLE	Hi-Speed Disable: disables the capability to attach as either a hi- or full-speed device, forcing full-speed attachment only (i.e., no hi-speed support).
		0 : hi-/full-speed 1 : full-speed only (hi-speed disabled)
4	MTT_ENABLE	Multi-TT Enable: enables one transaction translator per port operation.
		Selects between a mode where only one transaction translator is available for all ports (single-TT), or each port gets a dedicated transaction translator (multi-TT).
		0 : single TT for all ports 1 : multi-TT (one TT per port)
3	EOP_DISABLE	EOP Disable: disables End Of Packet (EOP) generation at End Of Frame Time #1 (EOF1) when in full-speed mode.
		During full-speed operation only, the hub can send EOP when no downstream traffic is detected at EOF1. See the <i>USB 2.0 Specification</i> , <i>Section 11.3.1</i> for details.
		0 : EOP generation is normal 1 : EOP generation is disabled
2:1	CURRENT_SNS	Over-Current Sense: selects current sensing on all ports (ganged); a port-by-port basis (individual); or none (for bus-powered hubs only). The ability to support current sensing on a ganged or port-by-port basis is hardware implementation dependent.
		00 : ganged sensing 01 : individual sensing 1x : over-current sensing not supported (use with bus-powered configurations)

BIT NUMBER	BIT NAME	DESCRIPTION
0	PORT_PWR	Port Power Switching: enables power switching on all ports (ganged) or a port-by-port basis (individual). The ability to support power enabling on a ganged or port-by-port basis is hardware implementation dependent.
		0 : ganged switching 1 : individual switching

# 5.1.8 Register 07h: Configuration Data Byte 2

	Trogiotor orini o	,
BIT NUMBER	BIT NAME	DESCRIPTION
7	DYNAMIC	Dynamic Power Enable: controls the ability of the hub to automatically change from self-powered to bus-powered operation if the local power source is removed or unavailable. It can also go from bus-powered to self-powered operation if the local power source is restored.
		When dynamic power switching is enabled, the hub detects the availability of a local power source by monitoring LOCAL_PWR. If the hub detects a change in power source availability, the hub immediately disconnects and removes power from all downstream devices. It also disconnects the upstream port. The hub will then re-attach to the upstream port as either a bus-powered hub (if local power is unavailable) or a self-powered hub (if local power is available).
		ino dynamic auto-switching     idynamic auto-switching capable
6	rsvd	
5:4	OC_TIMER	Over Current Timer Delay:
		00: 0.1 ms 01: 4.0 ms 10: 8.0 ms 11: 16.0 ms
3	COMPOUND	Compound Device: indicates the hub is part of a compound device (see the <i>USB Specification</i> for definition). The applicable port(s) must also be defined as having a non-removable device.
		<b>Note:</b> When configured via strapping options, declaring a port as non-removable automatically causes the hub controller to report that it is part of a compound device.
		0 : no 1 : yes, the hub is part of a compound device
2:0	rsvd	

# 5.1.9 Register 08h: Configuration Data Byte 3

BIT NUMBER	BIT NAME	DESCRIPTION
7:4	rsvd	
3	PRTMAP_EN	Port Mapping Enable: selects the method used by the hub to assign port numbers and disable ports.
		0 : standard mode 1 : port mapping mode
2:1	rsvd	
0	STRING_EN	Enables String Descriptor Support
		0 : string support disabled 1 : string support enabled

# 5.1.10 Register 09h: Non-Removable Device

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	NR_DEVICE	Non-Removable Device: indicates which port has a non-removable device.
		0 : port is removable 1 : port is non-removable
		Bit 7 : rsvd Bit 6 : rsvd Bit 5 : rsvd Bit 4 : controls port 4 Bit 3 : controls port 3 Bit 2 : controls port 2 Bit 1 : controls port 1 Bit 0 : rsvd
		<b>Note:</b> The device must provide its own descriptor data.  When using the default configuration, the NON_REM[1:0] pins will designate the appropriate ports as being non-removable.

## 5.1.11 Register 0Ah: Port Disable For Self-Powered Operation

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	PORT_DIS_SP	Port Disable Self-Powered: disables one or more ports.
		0 = port is available 1 = port is disabled
		Bit 7 : rsvd Bit 6 : rsvd Bit 5 : rsvd Bit 4 : controls port 4 Bit 3 : controls port 3 Bit 2 : controls port 2 Bit 1 : controls port 1 Bit 0 : rsvd
		During self-powered operation when mapping mode is disabled (PRTMAP_EN = 0), this register selects the ports that will be permanently disabled. These ports are then unavailable and cannot be enabled or enumerated by a host controller. The ports can be disabled in any order, where the internal logic will automatically report the correct number of enabled ports to the USB host. The active ports will be reordered in order to ensure proper function.
		When using the default configuration, PRT_DIS_P[x:1] and PRT_DIS_M[x:1] pins disable the appropriate ports.

## 5.1.12 Register 0Bh: Port Disable For Bus-Powered Operation

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	PORT_DIS_BP	Port Disable Bus-Powered: disables one or more ports.
		0 = port is available 1 = port is disabled
		Bit 7 : rsvd Bit 6 : rsvd Bit 5 : rsvd Bit 4 : controls port 4 Bit 3 : controls port 3 Bit 2 : controls port 2 Bit 1 : controls port 1 Bit 0 : rsvd
		During self-powered operation when mapping mode is disabled (PRTMAP_EN = 0), this selects the ports which will be permanently disabled. These ports are then unavailable and cannot be enabled or enumerated by a host controller. The ports can be disabled in any order, where the internal logic will automatically report the correct number of enabled ports to the USB host. The active ports will be reordered in order to ensure proper function.
		When using the internal default option, the PRT_DIS_P[x:1] and PRT_DIS_M[x:1] pins disable the appropriate ports.

## 5.1.13 Register 0Ch: Max Power For Self-Powered Operation

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	MAX_PWR_SP	Max Power Self-Powered: the value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a self-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value also includes the power consumption of a permanently attached peripheral if the hub is configured as a compound device. The embedded peripheral reports 0 mA in its descriptors.
		Note: The USB 2.0 Specification does not permit this value to exceed 100 mA

## 5.1.14 Register 0Dh: Max Power For Bus-Powered Operation

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	MAX_PWR_BP	Max Power Bus-Powered: the value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a bus-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value also includes the power consumption of a permanently attached peripheral if the hub is configured as a compound device. The embedded peripheral reports 0 mA in its descriptors.

## 5.1.15 Register 0Eh: Hub Controller Max Current For Self-Powered Operation

		<b>.</b>
BIT NUMBER	BIT NAME	DESCRIPTION
7:0	HC_MAX_C_SP	Hub Controller Max Current Self-Powered: the value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a self-powered hub. This value includes the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board. This value does NOT include the power consumption of a permanently attached peripheral if the hub is configured as a compound device.  Note: The USB 2.0 Specification does not permit this value to exceed 100 mA  A value of 50 (decimal) indicates 100 mA, which is the default value.

## 5.1.16 Register 0Fh: Hub Controller Max Current For Bus-Powered Operation

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	HC_MAX_C_BP	Hub Controller Max Current Bus-Powered: the value in 2 mA increments that the hub consumes from an upstream port (VBUS) when operating as a buspowered hub. This value will include the hub silicon along with the combined power consumption (from VBUS) of all associated circuitry on the board.
		Note: This value will not include the power consumption of a permanently attached peripheral if the hub is configured as a compound device.  A value of 50 (decimal) would indicate 100 mA, which is the default value.

### 5.1.17 Register 10h: Power-On Time

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	POWER_ON_TIME	Power-On Time: the length of time that it takes (in 2 ms intervals) from the time the host initiated the power-on sequence on a port until the port has adequate power.

# 5.1.18 Register 11h: Language ID High

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	LANG_ID_H	USB Language ID: upper 8 bits of a 16-bit ID field

### 5.1.19 Register 12h: Language ID Low

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	LANG_ID_L	USB Language ID: lower 8 bits of a 16-bit ID field

### 5.1.20 Register 13h: Manufacturer String Length

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	MFR_STR_LEN	Manufacturer String Length: with a maximum string length of 31 characters (when supported).

### 5.1.21 Register 14h: Product String Length

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	PRD_STR_LEN	Product String Length: with a maximum string length of 31 characters (when supported).

### 5.1.22 Register 15h: Serial String Length

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	SER_STR_LEN	Serial String Length: with a maximum string length of 31 characters (when supported).

### 5.1.23 Register 16h-53h: Manufacturer String

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	MFR_STR	Manufacturer String: UNICODE UTF-16LE per <i>USB 2.0 Specification</i> : with a maximum string length of 31 characters (when supported).
		Note: The string consists of individual 16-bit UNICODE UTF-16LE characters. The characters will be stored starting with the LSB at the least significant address and the MSB at the next 8-bit location. (Subsequent characters must be stored in sequential contiguous addresses in the same LSB, MSB manner.)  Warning: Close attention to the byte order of the selected programming
		tool should be monitored.

#### 5.1.24 Register 54h-91h: Product String

• • • • •		
BIT NUMBER	BIT NAME	DESCRIPTION
7:0	PRD_STR	Product String: UNICODE UTF-16LE per USB 2.0 Specification
		When supported, the maximum string length is 31 characters (62 bytes).
		Note: The string consists of individual 16-bit UNICODE UTF-16LE characters. The characters will be stored starting with the LSB at the least significant address and the MSB at the next 8-bit location. (Subsequent characters must be stored in sequential contiguous address in the same LSB, MSB manner.)  Warning: Close attention to the byte order of the selected programming tool should be manifered.
		tool should be monitored.

## 5.1.25 Register 92h-CFh: Serial String

BIT NUMBER	BIT NAME	DESCRIPTION
7:0	SER_STR	Serial String: UNICODE UTF-16LE per USB 2.0 specification
		When supported, the maximum string length is 31 characters (62 bytes).
		Note: The string consists of individual 16-bit UNICODE UTF-16LE characters. The characters will be stored starting with the LSB at the least significant address and the MSB at the next 8-bit location. (Subsequent characters must be stored in sequential contiguous address in the same LSB, MSB manner.)  Warning: Close attention to the byte order of the selected programming tool should be monitored.

### 5.1.26 Register D0h: Battery Charging Enable

		_ accord _ accord _ accord
BIT NUMBER	BIT NAME	DESCRIPTION
7:0	BC_EN	Battery Charging Enable: enables the battery charging feature for the corresponding port.
		<ul><li>0 : battery charging support is not enabled</li><li>1 : battery charging support is enabled</li></ul>
		Bit 7: rsvd Bit 6: rsvd Bit 5: rsvd Bit 4: controls port 4 Bit 3: controls port 3 Bit 2: controls port 2 Bit 1: controls port 1 Bit 0: rsvd

## 5.1.27 Register F6h: Boost\_Up

		_ ·
BIT NUMBER	BIT NAME	DESCRIPTION
7:2	rsvd	
1:0	BOOST_IOUT	USB electrical signaling drive strength boost bit for the upstream port.
		00 : normal electrical drive strength - no boost 01 : elevated electrical drive strength - low (~ 4% boost) 10 : elevated electrical drive strength - medium (~ 8% boost) 11 : elevated electrical drive strength - high (~12% boost)
		Note: Boost could result in non-USB compliant parameters. Therefore, a value of 00 should be implemented unless specific implementation issues require additional signal boosting to correct for degraded USB signalling levels.

### 5.1.28 Register F8h: Boost\_4:0

BIT NUMBER	BIT NAME	DESCRIPTION
7:6	BOOST_IOUT_4	USB electrical signaling drive strength boost bit for downstream port 4.
		00 : normal electrical drive strength - no boost 01 : elevated electrical drive strength - low (~4% boost) 10 : elevated electrical drive strength - medium (~ 8% boost) 11 : elevated electrical drive strength - high (~12% boost)
5:4	BOOST_IOUT_3	USB electrical signaling drive strength boost bit for downstream port 3.
		00 : normal electrical drive strength - no boost 01 : elevated electrical drive strength - low (~4% boost) 10 : elevated electrical drive strength - medium (~ 8% boost) 11 : elevated electrical drive strength - high (~12% boost)
3:2	BOOST_IOUT_2	USB electrical signaling drive strength boost bit for downstream port 2.  00: normal electrical drive strength - no boost 01: elevated electrical drive strength - low (~4% boost) 10: elevated electrical drive strength - medium (~ 8% boost) 11: elevated electrical drive strength - high (~12% boost)
1:0	BOOST_IOUT_1	USB electrical signaling drive strength boost bit for downstream port 1.  00 : normal electrical drive strength - no boost 01 : elevated electrical drive strength - low (~4% boost) 10 : elevated electrical drive strength - medium (~ 8% boost) 11 : elevated electrical drive strength - high (~12% boost)

**Note:** Boost could result in non-USB compliant parameters. Therefore, a value of 00 should be implemented unless specific implementation issues require additional signal boosting to correct for degraded USB signalling levels.

#### 5.1.29 Register FAh: Port Swap

00	rtogiotoi i 7 tiii. i	on onap
BIT NUMBER	BIT NAME	DESCRIPTION
7:0	PRTSP	Port Swap: swaps the upstream USBDP/USBDM pins (USBDP_UP and USBDM_UP) and the downstream USBDP/USBDM pins (USBDP_DN[x:1] and USBDP_DN[x:1]) for ease of board routing to devices and connectors.
		0 : USB D+ functionality is associated with the DP pin and D- functionality is associated with the DM pin.  1 : USB D+ functionality is associated with the DM pin and D- functionality is associated with the DP pin.
		Bit 7 : rsvd Bit 6 : rsvd Bit 5 : rsvd Bit 4 : controls port 4 Bit 3 : controls port 3 Bit 2 : controls port 2 Bit 1 : controls port 1 Bit 0 : when set to 1, the upstream port DP/DM is swapped.

## 5.1.30 Register FBh: PortMap 12

BIT NUMBER	BIT NAME		DESCRIPTION						
7:0	PRTR12	host controller, the hub is not permitt controller will num	PortMap Register for Ports 1 and 2: When a hub is enumerated by a USB host controller, the hub is only permitted to report how many ports it has; the hub is not permitted to select a numerical range or assignment. The host controller will number the downstream ports of the hub starting with the number 1, up to the number of ports that the hub reports having.						
		The host's port number is called the Logical Port Number and the phy port on the hub is the Physical Port Number. When mapping mode is enabled (see <b>PRTMAP_EN</b> , Section 5.1.9 on page 30) the hub's downstream port numbers can be mapped to different logical port num (assigned by the host).							
		Note: Contiguous logical port numbers must be implemented, starting from number 1 up to the maximum number of enabled ports. T ensures that the hub's ports are numbered in accordance with way a host will communicate with the ports.							
		Bit [7:4]	0000	Physical port 2 is disabled					
			0001	Physical port 2 is mapped to logical port 1					
			0010	Physical port 2 is mapped to logical port 2					
			0011	Physical port 2 is mapped to logical port 3					
			0100	Physical port 2 is mapped to logical port 4					
			1000 <b>to</b> 1111	rsvd, will default to 0000 value					
		Bit [3:0]	0000	Physical port 1 is disabled					
			0001	Physical port 1 is mapped to logical port 1					
			0010	Physical port 1 is mapped to logical port 2					
			0011	Physical port 1 is mapped to logical port 3					
			Physical port 1 is mapped to logical port 4						
			1000 <b>to</b> 1111	rsvd, will default to 0000 value					

## 5.1.31 Register FCh: PortMap 34

BIT NUMBER	BIT NAME	DESCRIPTION								
7:0	PRTR34	host controller, the hub is not permitte controller will num	PortMap Register for Ports 3 and 4: When a hub is enumerated by a USB host controller, the hub is only permitted to report how many ports it has; the hub is not permitted to select a numerical range or assignment. The host controller will number the downstream ports of the hub starting with the number 1, up to the number of ports that the hub reports having.							
		port on the hub is enabled (see <b>PRT</b> downstream port r	The host's port number is called the Logical Port Number and the physical port on the hub is the Physical Port Number. When mapping mode is enabled (see <b>PRTMAP_EN</b> , Section 5.1.9 on page 30) the hub's downstream port numbers can be mapped to different logical port numbers (assigned by the host).							
		from num ensures	Note: Contiguous logical port numbers must be implemented, starting from number 1 up to the maximum number of enabled ports. This ensures that the hub's ports are numbered in accordance with the way a host will communicate with the ports.							
		Bit [7:4]	0000	Physical port 4 is disabled						
			0001	Physical port 4 is mapped to logical port 1						
			0010	Physical port 4 is mapped to logical port 2						
			0011	Physical port 4 is mapped to logical port 3						
			0100	Physical port 4 is mapped to logical port						
			1000 <b>to</b> 1111	rsvd, will default to 0000 value						
		Bit [3:0]	0000	Physical port 3 is disabled						
			0001	Physical port 3 is mapped to logical port						
			0010	Physical port 3 is mapped to logical port 2						
			0011	Physical port 3 is mapped to logical port 3						
			0100	Physical port 3 is mapped to logical port						
			1000 <b>to</b>	rsvd, will default to 0000 value						

5.1.32	Register	FFh:	Status/Command
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· · · · · · ·	ragioto: i i iii o	
BIT NUMBER	BIT NAME	DESCRIPTION
7:3	rsvd	
2	INTF_PW_DN	SMBus Interface Power Down:
		0 : interface is active 1 : interface power down after ACK has completed
1	RESET	Reset the SMBus interface and internal memory back to RESET_N assertion default settings.
		0 : normal run/idle state 1 : force a reset of registers to their default state
0	USB_ATTACH	USB Attach (and write protect)
		0 : SMBus slave interface is active 1 : the hub will signal a USB attach event to an upstream device, and the internal memory (address range 0x00-0xFE) is write-protected to prevent unintentional data corruption.

## 5.2 I<sup>2</sup>C EEPROM

The hub can be configured via a 2-wire (I<sup>2</sup>C) EEPROM (256x8). See Table 5.1 for details on enabling the I<sup>2</sup>C EEPROM interface. The I<sup>2</sup>C EEPROM interface implements a subset of the I<sup>2</sup>C Master Specification (refer to the Philips Semiconductor Standard I<sup>2</sup>C-Bus Specification I<sup>2</sup>C protocol for details). The hub's interface is designed to attach to a single dedicated I<sup>2</sup>C EEPROM which conforms to the Standard-mode I<sup>2</sup>C specification (100 kbit/s transfer rate and 7-bit addressing) for protocol and electrical compatibility. The I<sup>2</sup>C EEPROM shares the same pins as the SMBus interface, therefore the SMBus interface is not available when the I<sup>2</sup>C EEPROM interface has been enabled (and vice versa).

The hub acts as the master and generates the serial clock SCL, controls the bus access (determines which device acts as the transmitter and which device acts as the receiver), and generates the START and STOP conditions. The hub will read the external EEPROM for configuration data and then attach to the upstream USB host.

Note: If no external EEPROM is present, the hub will write 0 to all configuration registers.

The hub does not have the capacity to write to the external EEPROM. The hub only has the capability to read from an external EEPROM. The external EEPROM will be read (even if it is blank), and the hub will be configured with the values that are read. Any values read for unsupported registers will not be retained (i.e., they will remain as the default values). Reserved registers should be set to 0 unless otherwise specified. EEPROM reset values are 0x00. Contents read from unavailable registers should be ignored.

## 5.2.1 I<sup>2</sup>C Slave Address

The 7-bit slave address is 1010000b.

Note: 10-bit addressing is not supported.

## 5.2.2 Protocol Implementation

The hub will only access an EEPROM using the sequential read protocol as outlined in Chapter 8 of MicroChip 24AA02/24LC02B [4].

## 5.2.3 Pull-Up Resistor

The circuit board designer is required to place external pull-up resistors (10 k $\Omega$  recommended) on the SDA/SMBDATA and SCL/SMBCLK/CFG\_SEL[0] lines (per *SMBus 1.0 Specification* [3], and EEPROM manufacturer guidelines) to VDD33 in order to assure proper operation.

## 5.2.4 In-Circuit EEPROM Programming

The EEPROM can be programmed via automatic test equipment (ATE) by pulling RESET\_N low (which tri-states the hub's EEPROM interface and allows an external source to program the EEPROM).

## 5.3 SMBus

The Microchip hub can be configured by an external processor via an SMBus interface (see Table 5.1 for details on enabling the SMBus interface). The SMBus interface shares the same pins as the EEPROM interface, and therefore the hub no longer supports the I<sup>2</sup>C EEPROM interface when the SMBus interface has been enabled. The hub waits indefinitely for the SMBus code load to complete and only appears as a newly connected device on USB after the code load is complete.

The hub's SMBus acts as a slave-only SMBus device. The implementation only supports block write (Section 5.3.2.1) and block read (Section 5.3.2.2) protocols, where the available registers are outlined in Section 5.1 on page 25. Reference the *System Management Bus Specification* [3] for additional information.

#### 5.3.1 SMBus Slave Address

The 7-bit slave address is 0101100b. The hub will not respond to the general call address of 0000000b.

## 5.3.2 Protocol Implementation

Typical block write and block read protocols are shown in figures 5.1 and 5.2. Register accesses are performed using 7-bit slave addressing, an 8-bit register address field, and an 8-bit data field. The shading shown in the figures during a read or write indicates the hub is driving data on the **SMBDATA** line; otherwise, host data is on the **SDA/SMBDATA** line.

The SMBus slave address assigned to the hub (0101100b) allows it to be identified on the SMBus. The register address field is the internal address of the register to be accessed. The register data field is the data that the host is attempting to write to the register or the contents of the register that the host is attempting to read.

Note: Data bytes are transferred MSB first.

#### 5.3.2.1 Block Write/Read

The block write begins with a slave address and a write condition. After the command code, the host issues a byte count which describes how many more bytes will follow in the message. If a slave had 20 bytes to send, the first byte would be the number 20 (14h), followed by the 20 bytes of data. The byte count may not be zero. A block write or read allows a transfer maximum of 32 data bytes.

**Note:** For the following SMBus tables:

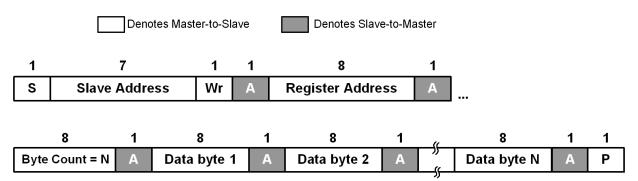


Figure 5.1 Block Write

#### 5.3.2.2 Block Read

A block read differs from a block write in that the repeated start condition exists to satisfy the I<sup>2</sup>C specification's requirement for a change in the transfer direction.



Figure 5.2 Block Read

## 5.3.2.3 Invalid Protocol Response Behavior

Note that any attempt to update registers with an invalid protocol will not be updated. The only valid protocols are write block and read block (described above), where the hub only responds to the 7-bit hardware selected slave address (0101100b). Also, the only valid registers for the hub are outlined in Section 5.1 on page 25. Attempts to access any other registers will return no response.

## 5.3.3 Slave Device Timeout

Devices in a transfer can abort the transfer in progress and release the bus when any single clock low interval exceeds 25 ms ( $T_{\text{TIMEOUT, MIN}}$ ). The master must detect this condition and generate a stop condition within or after the transfer of the interrupted data byte. Slave devices must reset their communication and be able to receive a new START condition no later than 35 ms ( $T_{\text{TIMEOUT, MAX}}$ ).

**Note:** Some simple devices do not contain a clock low drive circuit; this simple kind of device typically resets its communications port after a start or stop condition. The slave device timeout must be implemented.

## 5.3.4 Stretching the SCLK Signal

The hub supports stretching of the SCLK by other devices on the SMBus. However, the hub does not stretch the SCLK.

## 5.3.5 SMBus Timing

The SMBus slave interface complies with the SMBus Specification Revision 1.0 [3]. See Section 2.1, AC Specifications on page 3 for more information.

## 5.3.6 Bus Reset Sequence

The SMBus slave interface resets and returns to the idle state upon a START condition followed immediately by a STOP condition.

## 5.3.7 SMBus Alert Response Address

The SMBALERT# signal is not supported by the hub.

## 5.4 Default Configuration

To put the hub in the default configuration, strap CFG\_SEL[1:0] to 00b. This procedure configures the hub to the internal defaults and enables the strapping options. To place the hub in default configuration with overrides, see Table 5.1 on page 24 for the list of the options.

The internal default values are used for the registers that are not controlled by strapping option pins. Refer to Section 5.1 on page 25 for the internal default values that are loaded when this option is selected. For a list of strapping option pins, see Chapter 5 on page 24, and to configure the strapping pins, see Section 3.3.1 on page 20.

## 5.5 Reset

The hub experiences the following two resets:

- Hardware reset via the RESET N pin
- USB bus reset

## 5.5.1 External Hardware RESET N

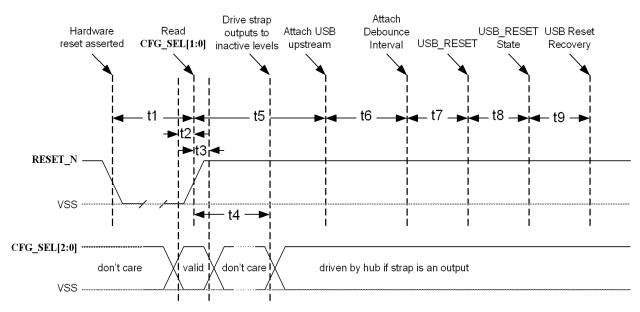
A valid hardware reset is defined as assertion of RESET\_N for a minimum of 1  $\mu$ s after all power supplies are within operating range. While reset is asserted, the hub (and its associated external circuitry) consumes less than 500  $\mu$ A of current from the upstream USB power source.

Assertion of RESET\_N causes the following:

- 1. All downstream ports are disabled, and PRTPWR[x:1] to downstream devices is removed (unless BC EN[x:1] is enabled).
- 2. The PHYs are disabled, and the differential pairs will be in a high-impedance state.
- 3. All transactions immediately terminate; no states are saved.
- 4. All internal registers return to the default state (in most cases, 00h).
- 5. The external crystal oscillator is halted.
- 6. The PLL is halted.

The hub is operational 500  $\mu$ s after RESET\_N is negated. Once operational, the hub will do one of the following, depending on configuration:

- Read the strapping pins (default configuration with strapping options enabled)
- Read configuration information from the external I<sup>2</sup>C EEPROM
- Wait for configuration over SMBus.



## 5.5.1.1 RESET\_N for Strapping Option Configuration

Figure 5.3 Reset\_N Timing for Default Configuration

NAME	DESCRIPTION	MIN	TYP	MAX	UNITS
t1	RESET_N asserted	1			μS
t2	CFG_SEL[1:0] setup time	16.7			ns
t3	CFG_SEL[1:0] hold time	16.7		1400	ns
t4	Hub outputs driven to inactive logic states		1.5	2	μS
t5	USB attach (see notes)		3		μS
t6	Host acknowledges attach and signals USB reset	100			ms
t7	USB_RESET		Host Defined		ms
t8	USB_RESET State	Note 5.1			ms
t9	USB Reset Recovery	10			ms

### Notes:

- When in bus-powered mode, the hub and its associated circuitry must not consume more than 100 mA from the upstream USB power source during t1+t5.
- All power supplies must have reached the operating levels mandated in Chapter 6: DC Parameters, prior to (or coincident with) the assertion of RESET N.

Note 5.1 10 ms for hubs, 50 ms for root ports.

## 5.5.1.2 RESET\_N for EEPROM Configuration

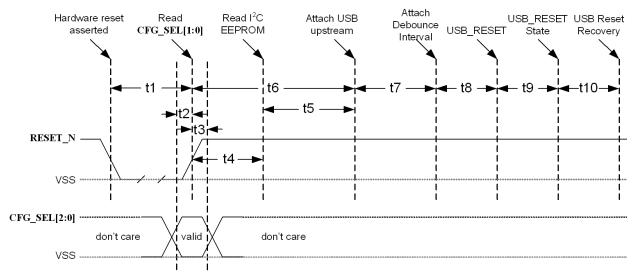


Figure 5.4 Reset\_N Timing for EEPROM Mode

NAME	DESCRIPTION	MIN	TYP	MAX	UNITS
t1	RESET_N asserted	1			μS
t2	CFG_SEL[1:0] setup time	16.7			ns
t3	CFG_SEL[1:0] hold time	16.7		1400	ns
t4	Hub recovery/stabilization			500	μS
t5	EEPROM read (hub configuration)		40		ms
t6	USB attach (see notes)		40		ms
t7	Host acknowledges attach and signals USB reset	100			ms
t8	USB_RESET		host- defined		ms
t9	USB_RESET state	Note 5.2			ms
t10	USB Reset Recovery	10			ms

#### Notes:

- When in bus-powered mode, the hub and its associated circuitry must not consume more than 100 mA from the upstream USB power source during t6+t7+t8+t9.
- All power supplies must have reached the operating levels mandated in Chapter 6: DC Parameters, prior to (or coincident with) the assertion of RESET\_N.

Note 5.2 10 ms for hubs, 50 ms for root ports.

## 5.5.1.3 RESET\_N for SMBus Slave Configuration

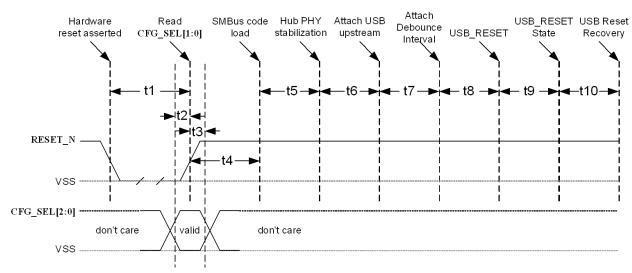


Figure 5.5 Reset\_N Timing for SMBus Mode

NAME	DESCRIPTION	MIN	TYP	MAX	UNITS
t1	RESET_N Asserted	1			μS
t2	CFG_SEL[1:0] setup time	16.7			ns
t3	CFG_SEL[1:0] hold time	16.7		1400	ns
t4	Hub recovery/stabilization			500	μS
t5	SMBus Code Load	2		1000	ms
t6	Hub configuration and USB attach		0		ms
t7	Host acknowledges attach and signals USB reset	100			ms
t8	USB_RESET		host- defined		ms
t9	USB_RESET State	Note 5.4			ms
t10	USB Reset Recovery	10			ms

Note 5.3 All power supplies must have reached the operating levels mandated in Chapter 6: *DC Parameters*, prior to (or coincident with) the assertion of RESET\_N.

Note 5.4 10 ms for hubs, 50 ms for root ports.

## 5.5.2 USB Bus Reset

In response to the upstream port signaling a reset to the hub, the hub does the following:

- 1. Sets default internal USB address to 0
- 2. Sets configuration to: unconfigured
- 3. Negates PRTPWR[x:1] to all downstream ports unless battery charging (BC\_EN[x:1]) is enabled
- 4. Clears all TT buffers
- 5. Moves device from suspended to active (if suspended)
- 6. Complies with Section 11.10 of the *USB 2.0 Specification* [1] for behavior after completion of the reset sequence. The host then configures the hub and the hub's downstream port devices in accordance with the *USB Specification*.

Note: The hub does not propagate the upstream USB reset to downstream devices.

# **Chapter 6 DC Parameters**

## 6.1 Maximum Guaranteed Ratings

PARAMETER	SYMBOL	MIN	MAX	UNITS	COMMENTS
Storage Temperature	T <sub>STOR</sub>	-55	150	°C	
Lead Temperature					Refer to JEDEC Specification J-STD-020D [5]
3.3 V supply voltage	VDD33 VDDA33		4.6	V	Applies to all packages
Voltage on any I/O pin		-0.5	5.5	V	
Voltage on XTALIN		-0.5	4.0	V	
Voltage on XTALOUT		-0.5	2.5	V	

#### Notes:

- Stresses above the specified parameters could cause permanent damage to the device. This is a stress rating only. Therefore, functional operation of the device at any condition above those indicated in the operation sections of this specification are not implied.
- When powering this device from laboratory or system power supplies, it is important that the absolute maximum ratings not be exceeded or device failure can result. Some power supplies exhibit voltage spikes on their outputs when the AC power is switched on or off. In addition, voltage transients on the AC power line may appear on the DC output. When this possibility exists, it is suggested that a clamp circuit be used.

## 6.2 Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	UNITS	COMMENTS
Extended Commercial Operating Temperature	T <sub>AE</sub>	0	85	°C	Ambient temperature in still air
Industrial Operating Temperature	T <sub>AI</sub>	-40	85	°C	Ambient temperature in still air Only applies to USB251xBi products
3.3 V supply voltage	VDD33 VDDA33	3.0	3.6	V	Applies to all parts
3.3 V supply rise time	t <sub>RT33</sub>	0	400	μS	See Figure 6.1 and Note 6.1

PARAMETER	SYMBOL	MIN	MAX	UNITS	COMMENTS
Voltage on any I/O pin		-0.3	5.5	V	If any 3.3 V supply voltage drops below 3.0 V, then the MAX becomes:  (3.3 V supply voltage) + 0.5
Voltage on XTALIN		-0.3	VDD33	V	

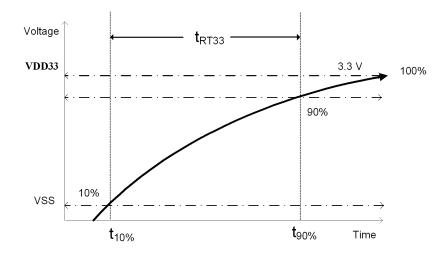


Figure 6.1 Supply Rise Time Model

Note 6.1 The rise time for the 3.3 V supply can be extended to 100 ms max if RESET\_N is actively driven low, typically by another IC, until 1  $\mu$ s after all supplies are within operating range.

**Table 6.1 DC Electrical Characteristics** 

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	COMMENTS
I, IS Type Input Buffer						
Low Input Level	V <sub>ILI</sub>			0.8	V	TTL Levels
High Input Level	V <sub>IHI</sub>	2.0			V	
Input Leakage	I <sub>IL</sub>	-10		+10	μА	$V_{IN} = 0$ to VDD33
Hysteresis (IS only)	V <sub>HYSI</sub>	250		350	mV	
Input Buffer with Pull-Up (IPU)						
Low Input Level	V <sub>ILI</sub>			0.8	V	TTL Levels
High Input Level	V <sub>IHI</sub>	2.0			V	
Low Input Leakage	I <sub>ILL</sub>	+35		+90	μА	V <sub>IN</sub> = 0
High Input Leakage	I <sub>IHL</sub>	-10		+10	μΑ	$V_{IN} = VDD33$

Table 6.1 DC Electrical Characteristics (continued)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	COMMENTS
Input Buffer with Pull-Down (IPD)						
Low Input Level	V <sub>ILI</sub>			0.8	V	TTL Levels
High Input Level	V <sub>IHI</sub>	2.0			V	
Low Input Leakage	I <sub>ILL</sub>	+10		-10	μΑ	V <sub>IN</sub> = 0
High Input Leakage	I <sub>IHL</sub>	-35		-90	μΑ	$V_{IN} = VDD33$
USB251xB/xBi ICLK Input Buffer						
Low Input Level	V <sub>ILCK</sub>			0.3	V	
High Input Level	V <sub>IHCK</sub>	0.9			V	
Input Leakage	I <sub>IL</sub>	-10		+10	μΑ	$V_{IN} = 0$ to VDD33
O12, I/O12 & I/OSD12 Type Buffer						
Low Output Level	V <sub>OL</sub>			0.4	V	I <sub>OL</sub> = 12 mA @ VDD33 = 3.3 V
High Output Level	V <sub>OH</sub>	2.4			V	I <sub>OH</sub> = -12 mA @ VDD33 = 3.3 V
Output Leakage	I <sub>OL</sub>	-10		+10	μА	
Hysteresis (SD pad only)	I <sub>HYSC</sub>	250		350	mV	V <sub>IN</sub> = VDD33 (Notes:)

Note 6.2 Output leakage is measured with the current pins in high impedance.

Note 6.3 See USB 2.0 Specification [1] for USB DC electrical characteristics.

Table 6.2 Supply Current Unconfigured: Hi-Speed Host (I<sub>CCINTHS</sub>)

PART	MIN	TYP	MAX	UNITS	COMMENTS
USB2512B/12Bi		40	45	mA	
USB2513B/13Bi		40	45	mA	
USB2514B/14Bi		45	50	mA	

Table 6.3 Supply Current Unconfigured: Full-Speed Host (I<sub>CCINTFS</sub>)

PART	MIN	TYP	MAX	UNITS	COMMENTS
USB2512B/12Bi		35	40	mA	
USB2513B/13Bi		35	40	mA	
USB2514B/14Bi		35	40	mA	

Table 6.4 Supply Current Configured: Hi-Speed Host (I<sub>HCH1</sub>)

PART	MIN	TYP	MAX	UNITS	COMMENTS
USB2512B		60	65	mA	
USB2512Bi		60	70	mA	
USB2513B		65	70	mA	This is the base current of one downstream
USB2513Bi		65	75	mA	port.
USB2514B		70	80	mA	
USB2514Bi		70	85	mA	
USB251xB/xBi Supply Current Configured Hi-Speed Host, each additional downstream port		1 port base +	1 port base +	mA	
		25 mA	25 mA		

Table 6.5 Supply Current Configured: Full-Speed Host (I<sub>FCC1</sub>)

PART	MIN	TYP	MAX	UNITS	COMMENTS
USB2512B		45	50	mA	
USB2512Bi		45	55	mA	
USB2513B		50	55	mA	Base current of one
USB2513Bi		50	60	mA	downstream port
USB2514B		50	60	mA	
USB2514Bi		50	65	mA	
USB251xB/xBi Supply Current Configured Full-Speed Host, each additional downstream port		1 port base +	1 port base +	mA	
		8 mA	8 mA		

Table 6.6 Supply Current Suspend (I<sub>CSBY</sub>)

PART	MIN	TYP	MAX	UNITS	COMMENTS
USB2512B		475	1000	μΑ	
USB2512Bi		475	1200	μА	
USB2513B		500	1100	μΑ	All aupplies sombined
USB2513Bi		500	1300	μА	All supplies combined
USB2514B		550	1200	μА	
USB2514Bi		550	1500	μА	

Table 6.7 Supply Current Reset (I<sub>CRST</sub>)

PART	MIN	TYP	MAX	UNITS	COMMENTS
USB2512B		550	1100	μΑ	
USB2512Bi		550	1250	μА	
USB2513B		650	1200	μΑ	All aupplies combined
USB2513Bi		650	1400	μА	All supplies combined
USB2514B		750	1400	μА	
USB2514Bi		750	1600	μА	

Table 6.8 Pin Capacitance

			LIMITS			
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Clock Input Capacitance	C <sub>XTAL</sub>			6	pF	All pins except USB pins and the pins under the test tied to AC ground
Input Capacitance	C <sub>IN</sub>			6	pF	(Note 6.4)
Output Capacitance	C <sub>OUT</sub>			6	pF	

Note 6.4 Capacitance  $T_A = 25^{\circ}C$ ; fc = 1 MHz; VDD33 = 3.3 V

## 6.2.1 Package Thermal Specifications

Thermal parameters are measured or estimated for devices with the exposed pad soldered to thermal vias in a multilayer 2S2P PCB per JESD51. Thermal resistance is measured from the die to the ambient air. The values provided are based on the package body, die size, maximum power consumption, 85°C ambient temperature, and 125°C junction temperature of the die.

SYMBOL	USB2512B/12Bi USB2513B/13Bi USB2514B/14Bi (°C/W)	VELOCITY (meters/s)
Θ	40.1	0
$\Theta_{JA}$	35.0	1
$\Psi_{JT}$	0.5	0
T JT	0.7	1
(A)	6.3	0
$\Theta_{\sf JC}$	6.3	1

Use the following formulas to calculate the junction temperature:

$$T_{J} = P \times \Theta_{JA} + T_{A}$$

$$T_{J} = P \times \Psi_{JT} + T_{T}$$

$$T_{J} = P \times \Theta_{JC} + T_{C}$$

# Max Power Supported = $(T_{J \text{ Max. Spec.}} \times T_{Amb.})/ \Theta_{JA}$

Table 6.9 Legend

SYMBOL	DESCRIPTION
T <sub>J</sub>	Junction temperature
Р	Power dissipated
$\Theta_{JA}$	Junction-to-ambient-temperature
ΘJC	Junction-to-top-of-package
Ψјт	Junction-to-bottom-of-case
T <sub>A</sub>	Ambient temperature
T <sub>C</sub>	Temperature of the bottom of the case
T <sub>T</sub>	Temperature of the top of the case

## **Chapter 7 AC Specifications**

## 7.1 Oscillator/Crystal

Crystal: Parallel resonant, fundamental mode, 24 MHz  $\pm 350$  ppm.

Note: The USB251xB/xBi contains an internal 1 M $\Omega$  resistor between the XTALIN and XTALOUT pins.

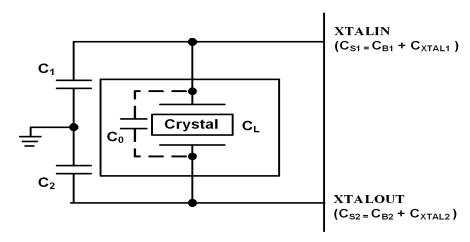


Figure 7.1 Typical Crystal Circuit

Table 7.1 Crystal Circuit Legend

SYMBOL	DESCRIPTION	IN ACCORDANCE WITH			
<b>C</b> <sub>0</sub>	Crystal shunt capacitance	Crystal manufacturar's apposition (Note 7.1)			
CL	Crystal load capacitance	Crystal manufacturer's specification (Note 7.1)			
<b>C</b> B	Total board or trace capacitance	OEM board design			
<b>C</b> <sub>S</sub>	Stray capacitance	Microchip IC and OEM board design			
C <sub>XTAL</sub>	XTAL pin input capacitance	Microchip IC			
<b>C</b> <sub>1</sub>	Load capacitors installed on OEM	Calculated values haved as Figure 7.0 (Nata 7.0)			
<b>C</b> <sub>2</sub>	- board	Calculated values based on Figure 7.2 (Note 7.2)			

$$C_1 = 2 \times (C_L - C_0) - C_{S1}$$

$$C_2 = 2 \times (C_L - C_0) - C_{S2}$$

Figure 7.2 Formula to Find the Value of C<sub>1</sub> and C<sub>2</sub>

Note 7.1  $C_0$  is usually included (subtracted by the crystal manufacturer) in the specification for  $C_L$  and should be set to 0 for use in the calculation of the capacitance formulas in Figure 7.2. However, the PCB itself may present a parasitic capacitance between XTALIN and XTALOUT. For an accurate calculation of  $C_1$  and  $C_2$ , take the parasitic capacitance between traces XTALIN and XTALOUT into account.

Note 7.2 Each of these capacitance values is typically around 18 pF.

## 7.2 External Clock

50% duty cycle  $\pm$  10%, 24 MHz  $\pm$  350 ppm, jitter < 100 ps rms.

The external clock is recommended to conform to the signaling level designated in the *JESD76-2 Specification* [5] on 1.2 V CMOS Logic. **XTALOUT** should be treated as a weak (<1mA) buffer output.

## 7.2.1 SMBus Interface

The hub conforms to all voltage, power, and timing characteristics and specifications as set forth in the *SMBus 1.0 Specification* [3] for slave-only devices (except as noted in Section 5.3: *SMBus* on page 40.

## 7.2.2 I<sup>2</sup>C EEPROM

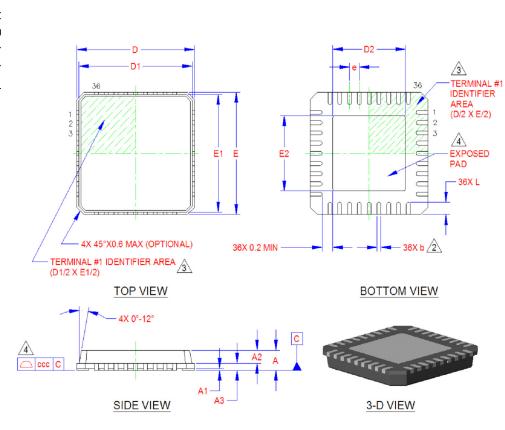
Clock frequency is fixed at 60 kHz  $\pm\,20\%.$ 

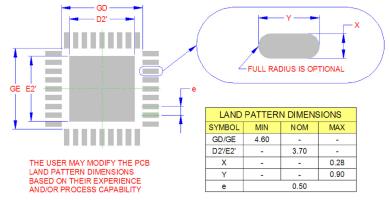
## 7.2.3 USB 2.0

The Microchip hub conforms to all voltage, power, and timing characteristics and specifications as set forth in the USB 2.0 Specification [1].

DS00001692A-page 55

Note: For the most current package drawings, see the Microchip Packaging Specification at http://www.microchip.com/packaging.





#### RECOMMENDED PCB LAND PATTERN

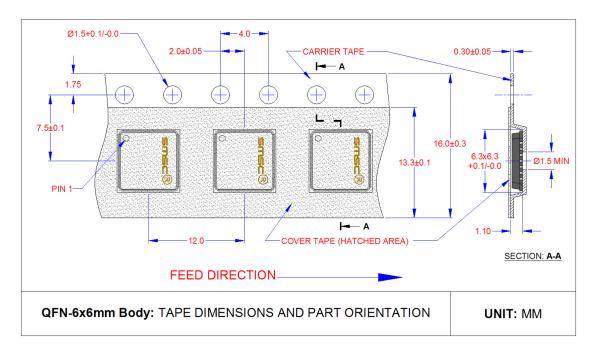
	COMMON DIMENSIONS					
SYMBOL	MIN	NOM	MAX	NOTE	REMARK	
Α	0.80	-	1.00	-	OVERALL PACKAGE HEIGHT	
A1	0	0.02	0.05	-	STANDOFF	
A2	0.60	-	0.80	-	MOLD CAP THICKNESS	
А3	0.20 REF			-	LEADFRAME THICKNESS	
D/E	5.85	6.00	6.15	-	X/Y BODY SIZE	
D1/E1	5.55	-	5.95	-	X/Y MOLD CAP SIZE	
D2/E2	3.55	3.70	3.85	2	X/Y EXPOSED PAD SIZE	
L	0.50	0.60	0.75	-	TERMINAL LENGTH	
b	0.18	0.25	0.30	2	TERMINAL WIDTH	
e		0.50 BSC		-	TERMINAL PITCH	

#### NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. POSITION TOLERANCE OF EACH TERMINAL AND EXPOSED PAD IS  $\pm\,0.05$ mm AT MAXIMUM MATERIAL CONDITION. DIMENSIONS "b" APPLIES TO PLATED TERMINALS AND IT IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
- DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE AREA INDICATED.
- 4. COPLANARITY ZONE APPLIES TO EXPOSED PAD AND TERMINALS.

Figure 8.1 36-Pin QFN, 6x6 mm Body, 0.5 mm Pitch

## 8.1 Tape and Reel Specifications



## TAPE LENGTH & PART QUANTITY

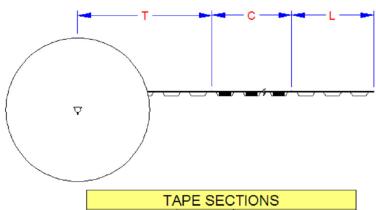


Figure 8.2 36-Pin Package Tape Specifications

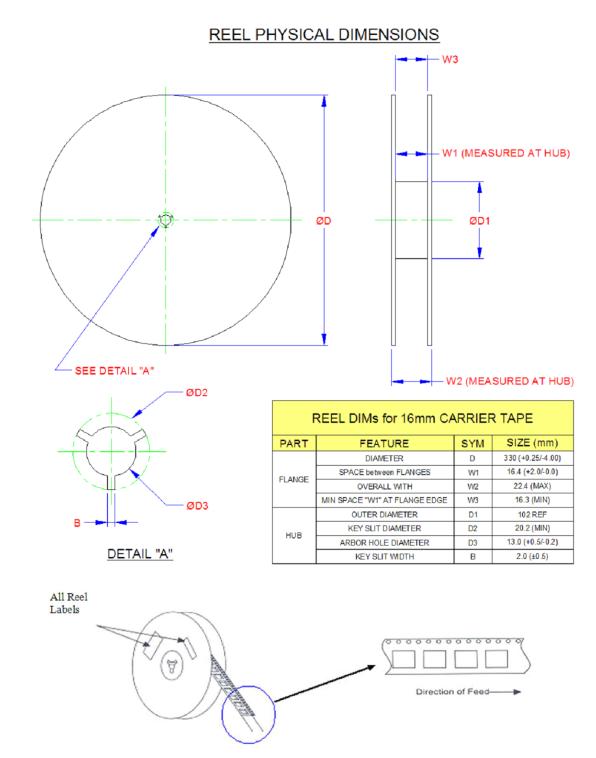


Figure 8.3 36-Pin Package Reel Specifications

# **Appendix A (Acronyms)**

I<sup>2</sup>C<sup>®</sup>: Inter-Integrated Circuit<sup>1</sup>

**OCS:** Over-Current Sense

PCB: Printed Circuit Board

PHY: Physical Layer

PLL: Phase-Locked Loop

QFN: Quad Flat No Leads

RoHS: Restriction of Hazardous Substances Directive

SCL: Serial Clock

SIE: Serial Interface Engine

SMBus: System Management Bus

TT: Transaction Translator

<sup>1.</sup>I<sup>2</sup>C is a registered trademark of Philips Corporation.

# **Appendix B (References)**

- [1] Universal Serial Bus Specification, Version 2.0, April 27, 2000 (12/7/2000 and 5/28/2002 Errata) USB Implementers Forum, Inc. http://www.usb.org
- [2] I<sup>2</sup>C-Bus Specification Version 1.1 NXP (formerly a division of Philips). http://www.nxp.com
- [3] System Management Bus Specification, version 1.0 SMBus. http://smbus.org/specs/
- [4] MicroChip 24AA02/24LC02B (Revision C) Microchip Technology Inc. http://www.microchip.com/
- [5] JEDEC Specifications: JESD76-2 (June 2001) and J-STD-020D.1 (March 2008)

  JEDEC Global Standards for the Microelectronics Industry. http://www.jedec.org/standards-documents

# **Data Sheet Revision History**

## **Revision History**

REVISION LEVEL & DATE	SECTION/FIGURE/ENTRY	CORRECTION				
REV A	REV A replaces previous SMSC version Rev. 2.4 (11-08-13).					
	Document is Microchip branded, mention of SMSC is removed.					
	Order numbers modified addin	g "G" or "C" as last character to suffix.				
	The following note added to Pa "For the most current package Specification at http://www.mic	drawings, see the Microchip Packaging				
Rev. 2.4 (11-08-13)	Section 5.2.1: I2C Slave Address	Corrected slave address to "1010000b".				
	Figure 3.1, Figure 3.2, Figure 3.3, Table 3.1	Corrected pin 36 name (VDDA33).				
	Section 5.5.1.1: RESET_N for Strapping Option Configuration	Updated timing diagram and values. Changed t6, t7, t8 name and added new t9. Updated t5 and 78 values.				
	Section 5.5.1.2: RESET_N for EEPROM Configuration	Updated timing diagram and values. Changed t7, t8, and t9 name and added new t10. Updated t5, t6, and t9 values.				
	Section 5.5.1.3: RESET_N for SMBus Slave Configuration	Updated timing diagram and values. Changed t7, t8, and t9 name and added new t10. Updated t5, t6, and t9 values. Removed t5 "bus" and "self" distinction.				
	Note 6.1	Added note regarding 3.3 V supply rise time.				
Rev. 2.3 (06-11-13)	Table 3.1: USB251xB/xBi Pin List (Alphabetical) on page 14	Corrected errant description "Server Message Block" to "System Management Bus".				
	Section 7.1: Oscillator/Crystal on page 53 and Figure 7.1: Typical Crystal Circuit on page 53	Updated figure to remove external 1 $\text{M}\Omega$ requirement. Added note indicating the device includes and internal1 $\text{M}\Omega$ resistor between the XTALIN and XTALOUT pins.				
	Figure 3.3: 4-Port 36-Pin QFN on page 13	Corrected typo on pin 6.				
	Figure 3.1: 2-Port 36-Pin QFN on page 11 & Table 3.1: USB251xB/xBi Pin List (Alphabetical) on page 14	Added alternate port disable functions to pins 1-4 of the USB2512B.				
Rev. 2.2 (02-17-12)	Cover	Updated clock bullet to remove reference to 48MHz clock support.				

## **Revision History (continued)**

REVISION LEVEL & DATE	SECTION/FIGURE/ENTRY	CORRECTION
	Section 1.1: Configurable Features on page 8	Updated bulleted lists. USB signal drive strength, USB differential pair pin location and downstream port power control / over-current detection items moved from first (strap-configurable) bulleted list to the second (EEPROM-configurable) bulleted list. Added enabling of battery charging to the first bulleted list.
	Section 3.1: Pin Configurations on page 11	Clarified introductory sentence.
	Table 3.2: USB251xB/xBi Pin Descriptions on page 17	Updated VBUS_DET buffer type to "I" and changed description to: "For self-powered applications with a permanently attached host, this pin must be connected to a dedicated host control output, or connected to the 3.3 V domain that powers the host (typically VDD33)."
	Table 3.2: USB251xB/xBi Pin Descriptions on page 17	Updated CRFILT and PLLFILT pin descriptions.
	Section 7.1: Oscillator/Crystal on page 53	Removed redundant sentence: "External Clock: 50% duty cycle ± 10%, 24/48 MHz ± 350 ppm, jitter < 100 ps rms". This information is provided in Section 7.2: External Clock on page 54.
	Chapter 7: AC Specifications	Removed ceramic resonator information.
	Section 7.2: External Clock	Replaced "1.8 V CMOS Logic" with "1.2 V CMOS Logic". Updated XTALOUT description.
	Section 3.3: Pin Descriptions (Grouped by Function)	Updated CRFILT and PLLFILT pin descriptions.
	Cover, Package, All	Removed the 49-BGA option.
	Order Code Page	Changed ordering codes for non-industrial USB2513B and USB2514B. Last character was changed from "G" to "C".
	Front page	Removed support for ceramic resonator.
Rev. 2.1 (02/22/11)	Section 6.2.1, Package Thermal Specifications	Added Max Power Supported = ( <b>T</b> J, max.spec <b>T</b> amb)/
Rev. 2.0 (10/01/10)	All	General refresh, corrected grammatical errors and unified tone.

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